HIGH POWER, BACK-CONTACT, THIN FILM RESISTOR

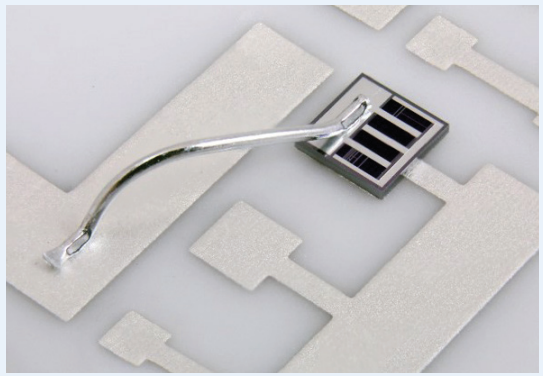
WIRE BONDABLE SILICON CHIP RESISTOR

KEY FEATURES

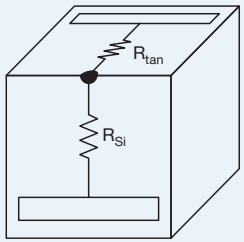
- Sintering, soldering, and epoxy attachment method options
- Low inductance
- Only one wire bond required – up to 6 mils diameter
- Moisture-resistant
- Small size, high power density

APPLICATIONS

- Gate resistor for silicon carbide MOSFET and IGBT-based power converters
- Current limiting for LED lighting
- High power
- Alternative energy
- Hybrid assemblies

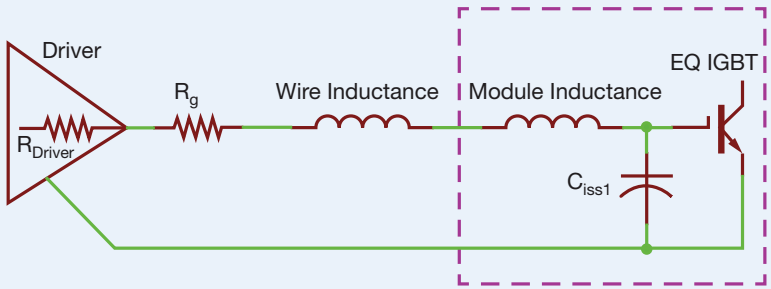


BACK CONTACT SCHEMATIC



$R_{total} = R_{tan} + R_{Si}$

SIMPLIFIED ELECTRICAL MODEL OF THE CIRCUIT



POWER RATING COMPARISONS

Part Type	Case Size	Power Rating
Thin film wire bondable, back-contact resistor on silicon	0808	Up to 4 W
Thin film surface-mount resistor on AlN	2512	Up to 6 W
Thick film chip resistor on AlN	2512	3.5 W

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